

Title (en)

FLUX FOR SOLDER PASTE AND SOLDER PASTE

Title (de)

FLUSSMITTEL FÜR EINE LÖTPASTE UND LÖTPASTE

Title (fr)

FLUX POUR PÂTE À SOUDER ET PÂTE À SOUDER

Publication

**EP 3804902 A4 20220316 (EN)**

Application

**EP 19811838 A 20190528**

Priority

- JP 2018106468 A 20180601
- JP 2019021024 W 20190528

Abstract (en)

[origin: EP3804902A1] Provided are: a flux that is for a solder paste and that can inhibit occurrence of voids; and a solder paste using the flux. This flux for a solder paste contains rosin, an imidazole compound, and a solvent, wherein the contained amount of the imidazole compound is 25-35 mass%. The flux also contains 0-20 mass% of a block organic acid and 0-3 mass% of an activator.

IPC 8 full level

**B23K 35/363** (2006.01); **B23K 35/02** (2006.01); **B23K 35/26** (2006.01); **B23K 35/36** (2006.01); **B23K 35/362** (2006.01); **C22C 13/00** (2006.01); **C22C 13/02** (2006.01)

CPC (source: EP KR US)

**B23K 35/025** (2013.01 - EP US); **B23K 35/26** (2013.01 - KR); **B23K 35/262** (2013.01 - EP US); **B23K 35/3612** (2013.01 - EP); **B23K 35/3613** (2013.01 - US); **B23K 35/3616** (2013.01 - KR); **B23K 35/362** (2013.01 - EP US); **C22C 13/00** (2013.01 - EP KR US); **C22C 13/02** (2013.01 - EP)

Citation (search report)

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- [XI] US 2004129344 A1 20040708 - ARITA HITOSHI [JP], et al
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Designated contracting state (EPC)

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**EP 3804902 A1 20210414**; **EP 3804902 A4 20220316**; **EP 3804902 B1 20230405**; BR 112020024143 A2 20210302; BR 112020024143 B1 20231128; CN 112262013 A 20210122; CN 112262013 B 20211026; HU E061616 T2 20230728; JP 2019209346 A 20191212; JP 6617793 B2 20191211; KR 102256446 B1 20210525; KR 20210002746 A 20210108; LT 3804902 T 20230525; MX 2020012706 A 20220131; MY 185259 A 20210430; PH 12020552043 A1 20210607; RS 64194 B1 20230630; TW 202016220 A 20200501; TW I710603 B 20201121; US 11167380 B2 20211109; US 2021213569 A1 20210715; WO 2019230694 A1 20191205

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